# Advanced/MA User-Installable Upgrades

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This document applies only to standard Advanced/MA baseboards with BIOS identifier .BU0.

The devices listed below are categorized according to two levels of qualification:

**Full Functional Tested:** The device has passed electrical and functional testing across the full temperature and voltage specifications for the product, as well as signal quality analysis and vendor specification analysis per the Full Functional Test Qualification Procedure for the particular device. The testing of the device may have been conducted by the vendor or other third party.

**Basic Functional Tested:** The device has passed basic functional testing at ambient temperatures per the Basic Functional Test Qualification Procedure for the particular device. The testing of the device may have been conducted by the vendor or other third party.

Devices are added to the list upon written notification to Intel that the device has passed all the requirements documented in the applicable test procedure. Devices not listed can be used, but in the event of unreliable system operation, the devices should be replaced with tested devices to determine whether the unlisted devices are causing the problem.

### **IMPORTANT NOTE:**

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### SYSTEM MEMORY

Table A-1 shows the possible memory combinations. The Advanced/MA will support both Fast Page DRAM or EDO DRAM SIMMs, but they cannot be mixed within the same memory bank. If Fast Page DRAM and EDO DRAM SIMMs are installed in separate banks, each bank will be optimized for maximum performance. Parity generation and detection is NOT supported, but parity SIMMs (x36) may be used. SIMM requirements are 70ns Fast Page Mode or 60nS EDO DRAM (70 ns EDO may be used with a 60mhz or slower external CPU clock) with tin-lead connectors.

SIMM 1,2 (Bank 0) SIMM Type (Amount)	SIMM 3,4 (Bank 1) SIMM Type (Amount)	Total System Memory
1M X 32 (4 MB)	Empty	8 MB
1M X 32 (4 MB)	1M X 32 (4 MB)	16 MB
1M X 32 (4 MB)	2M X 32 (8 MB)	24 MB
1M X 32 (4 MB)	4M X 32 (16 MB)	40 MB
1M X 32 (4 MB)	8M X 32 (32 MB)	72 MB
2M X 32 (8 MB)	Empty	16 MB
2M X 32 (8 MB)	1M X 32 (4 MB)	24 MB
2M X 32 (8 MB)	2M X 32 (8 MB)	32 MB
2M X 32 (8 MB)	4M X 32 (16 MB)	48 MB
2M X 32 (8 MB)	8M X 32 (32 MB)	80 MB
4M X 32 (16 MB)	Empty	32 MB
4M X 32 (16 MB)	1M X 32 (4 MB)	40 MB
4M X 32 (16 MB)	2M X 32 (8 MB)	48 MB
4M X 32 (16 MB)	4M X 32 (16 MB)	64 MB
4M X 32 (16 MB)	8M X 32 (32 MB)	96 MB
8M X 32 (32 MB)	Empty	64 MB
8M X 32 (32 MB)	1M X 32 (4 MB)	72 MB
8M X 32 (32 MB)	2M X 32 (8 MB)	80 MB
8M X 32 (32 MB)	4M X 32 (16 MB)	96 MB
8M X 32 (32 MB)	8M X 32 (32 MB)	128 MB

Table A-1. Possible SIMM memory combinations

Note: SIMMs may be parity (x 36) or non-parity (x 32)

### **IMPORTANT NOTE**

SIMMs with gold contacts should NOT be placed into SIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has resulted in unreliable memory operation. Use only Tin-lead contact SIMMs.

## **TESTED SIMM VENDORS**

The following tables list SIMMs that have been tested. SIMMs that are not listed should also function properly as long as their specifications are compatible with the devices listed below. In general, SIMM devices that are faster than those specified for a given platform will work, although no extra performance will be realized.

All Sizes: Tin-lead contacts.

## **FAST PAGE SIMM**

Vendor	Qual	Vendor Part Number	Comments		
1M x 32 (4MB), Non-Parity - 70ns					
Centon Memory	FULL	CPCB00104-7	Samsung DRAM		
Centon Memory	FULL	CSAM1MX32-70SMT or 60SMT			
Centon Memory	FULL	CSAM1MX32NT7SMT			
Century Microelectronics Inc.	FULL	3216M6-07T			
Fujitsu Ltd	FULL	158101	NPNX DRAM 1MX4		
Hyundai	FULL	HYM532100AM-70			
Hyundai	FULL	HYM532100AM-60B			
Hyundai	FULL	HYM532120W-70	HY532120w-7MA		
Micron Technology	FULL	MT8D132M-7			
Oki Semiconductor	FULL	MSC23132C-70DS8			
Samsung Corning Co, LTD.	FULL	KMM5321000BV-7			
Samsung Corning Co, LTD.	FULL	KMM5321000CV-7			
Samsung Corning Co, LTD.	FULL	KMM5321000AW-7			
Smart Modular Technologies	FULL	SMI5321000-7			
Smart Modular Technologies	FULL	SMI5321000W-7			
Smart Modular Technologies	FULL	SM5321000H-7			
Smart Modular Technologies	FULL	INSM5321000T-7			
Smart Modular Technologies	FULL	IN5321000-W7	with NEC DRAM		
Smart Modular Technologies	FULL	NI532014081XXS7	Hitachi devices Hm514405cs6		

1M x 32 (4MB), Non-Parity - 70ns (cont.)

Vandan	01	Vandan Dark Number	1
Vendor	Qual	Vendor Part Number	Comments
Smart Modular Technologies	FULL	INSM5321000-70	
Smart Modular Technologies	FULL	IN5321000W-7	Siemens 1X16 DRAM
Smart Modular Technologies	FULL	INSM5321000-7	with NEC 424400-70
Smart Modular Technologies	FULL	IN5321000W-7	with NEC 4218160-60,70
Texas Instruments	FULL	Z124BBK32S-70 IN	TM124BBK32S-70
Texas Instruments	FULL	TM124BBK32S-60	TWITE-IDBROZE TO
			TI# TM404DDI/2011 70
Texas Instruments	FULL	Z124BBK32U-70	TI# TM124BBK32U-70
Toshiba Corporation	FULL	THM3210B0AS-70	
Unigen Corporation	FULL	UG8M132SQT-70	
Unigen Corporation	FULL	NU53201400IXXS7	
Advantage Memory Corp.	BASIC	AMC1x32-70T	
Celestica Inc.	BASIC	CL001D01320B00J-70	
		KTM1x32L-70T	
Kingston Technology Corp.	BASIC		
Simple Technology	BASIC	STI321000-70T	
Super PC Memory	BASIC	4000/72NP	TIN must be specified when ordering
Unigen Corporation	BASIC	1x32UG7PBT1	
Unigen Corporation	BASIC	1x32UG7SQT	
Viking Components	BASIC	1x32-70T	
VisionTek Inc.	BASIC	VT69130.0	
	1	1M x 32 (4MB), Non-Parity	
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT8D132M-6	
1st Tech Corporation	BASIC	20-132-60T	
VisionTek Inc.	BASIC	VT69030.0	
VIGIOTITICA IIIO.	DAGIO		7000
		1M x 36 (4MB), Parity - 7	
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT9D136M-70	
Simple Technology	BASIC	STI361000-70T	
VisionTek Inc.	BASIC	VT69110.0	
Workstation Direct	BASIC	MM1x36-70T12C	
Workstation Direct	DAGIO		20no
	· ·	1M x 36 (4MB), Parity - 6	
		Vandar Part Number	
Vendor	Qual	Vendor Part Number	Comments
Vendor	Quai	Vendor Fart Number	Comments
Vendor	Quai		
Vendor	Qual	2M x 32 (8MB), Non-Parity	- 70ns
Vendor	Qual	2M x 32 (8MB), Non-Parity Vendor Part Number	
Vendor Hyundai	<b>Qual</b> FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70	- 70ns
Vendor Hyundai Micron Technology	<b>Qual</b> FULL FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7	- 70ns
Vendor Hyundai Micron Technology Micron Technology	Qual FULL FULL FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor	Qual FULL FULL FULL FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6 MSC23232C-70DS16	- 70ns
Vendor Hyundai Micron Technology Micron Technology	Qual FULL FULL FULL FULL FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor	Qual FULL FULL FULL FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6 MSC23232C-70DS16	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD.	Qual FULL FULL FULL FULL FULL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6 MSC23232C-70DS16 KMM5322000BV-7	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6 MSC23232C-70DS16 KMM5322000BV-7 KMM5322000CV-7 SMI5322000-7	- 70ns Comments
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7	- 70ns  Comments  using 1 x 16 devices
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity Vendor Part Number HYM532200AM-70 MT16D232M-7 MT16D232M-6 MSC23232C-70DS16 KMM5322000BV-7 KMM5322000CV-7 SMI5322000-7 NI532023101XXS7 Z248CBK32S-70 IN	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN	- 70ns  Comments  using 1 x 16 devices
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70  AMC2x32-70T	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc.	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp.	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-60 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation Unigen Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation Unigen Corporation Viking Components	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation Unigen Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1	- 70ns  Comments  using 1 x 16 devices TM248CBK32S-70
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation Unigen Corporation Viking Components	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0	- 70ns  - Comments  using 1 x 16 devices  TM248CBK32S-70  TM248CBK32S-60
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  Z248CBK32S-70T  CL001D02320B00J-70  KTM2x32L-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity	- 70ns  - Comments  using 1 x 16 devices  TM248CBK32S-70  TM248CBK32S-60  - 60ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  Z248CBK32S-70T  CL001D02320B00J-70  KTM2x32L-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number	- 70ns  - Comments  using 1 x 16 devices  TM248CBK32S-70  TM248CBK32S-60
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  Z248CBK32S-70T  CL001D02320B00J-70  KTM2x32L-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number	- 70ns  - Comments  using 1 x 16 devices  TM248CBK32S-70  TM248CBK32S-60  - 60ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology 1st Tech Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  Z448CBK32S-70T  CL001D02320B00J-70  KTM2x32L-70T  CL001D02320B00J-70  XTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number  MT16D232M-6  20-232-60T	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  Z248CBK32S-70T  CL001D02320B00J-70  KTM2x32L-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number	- 70ns  - Comments  using 1 x 16 devices  TM248CBK32S-70  TM248CBK32S-60  - 60ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology 1st Tech Corporation	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000BV-7  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  Z448CBK32S-70T  CL001D02320B00J-70  KTM2x32L-70T  CL001D02320B00J-70  XTM2x32L-70T  STI322000-70T  2x32UG7DBT  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number  MT16D232M-6  20-232-60T	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology 1st Tech Corporation 1st Tech Corporation Simple Technology	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7PBT1  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number  MT16D232M-6  20-232-60T  20-232-60T  20-232-60T  STI322000-60T	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology 1st Tech Corporation 1st Tech Corporation Simple Technology Simple Technology Simple Technology	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7PBT1  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number  MT16D232M-6  20-232-60T  20-232-60T  STI322000-60T  STI322000-60T  STI322000-60T	- 70ns
Vendor Hyundai Micron Technology Micron Technology Oki Semiconductor Samsung Corning Co, LTD. Samsung Corning Co, LTD. Smart Modular Technologies Smart Modular Technologies Texas Instruments Texas Instruments Toshiba Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. Simple Technology Unigen Corporation Unigen Corporation Viking Components VisionTek Inc.  Vendor Micron Technology 1st Tech Corporation 1st Tech Corporation Simple Technology	Qual FULL FULL FULL FULL FULL FULL FULL FUL	2M x 32 (8MB), Non-Parity  Vendor Part Number  HYM532200AM-70  MT16D232M-7  MT16D232M-6  MSC23232C-70DS16  KMM5322000CV-7  SMI5322000-7  NI532023101XXS7  Z248CBK32S-70 IN  Z248CBK32S-70 IN  THM3220C0AS-70  AMC2x32-70T  CL001D02320B00J-70  KTM2x32L-70T  STI322000-70T  2x32UG7PBT1  2x32UG7PBT1  2x32-70T  VT69150.0  2M x 32 (8MB), Non-Parity  Vendor Part Number  MT16D232M-6  20-232-60T  20-232-60T  20-232-60T  STI322000-60T	- 70ns

2M x 36 (8MB), Parity - 70ns

Vendor	Qual	Vendor Part Number	Comments
	FULL		Comments
Micron Technology		MT24D236M-7	
Micron Technology	FULL	MT18D236M-7	
Micron Technology	FULL	MT18D236M-6	
Simple Technology	BASIC	STI362000A-70T	
VisionTek Inc.	BASIC	VT69120.0	
Workstation Direct	BASIC	MM2x36-70T24C	
	•	2M x 36 (8MB), Parity - (	60ns
Vendor	Qual	Vendor Part Number	Comments
70			
	I.	4M x 32 (16MB), Non-Parity	v - 70ns
Vendor	Qual	Vendor Part Number	Comments
			Comments
Micron Technology	FULL	MT8D432M-7	
Micron Technology	FULL	MT8D432M-6	*** 00001575
Smart Modular Technologies	FULL	SM532044004X357	*** OBSOLETE
Celestica Inc.	BASIC	CL001D04320B00J-70	
Kingston Technology Corp.	BASIC	KTM4x32L-70T	
Simple Technology	BASIC	STI324000-70T	
Unigen Corporation	BASIC	4x32UG7KBT2	
Viking Components	BASIC	4x32-70T	
VisionTek Inc.	BASIC	VT69160.0	
		4M x 32 (16MB), Non-Parity	y - 60ns
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT8D432M-6	
Samsung Corning Co., Ltd	FULL	KMM5324100AK-6	
Texas Instruments	FULL	TM497BBK32S-60	
1st Tech Corporation	BASIC	20-432-60NT3	
Advantage Memory Corp.	BASIC	AMC4x32-60T	
Simple Technology	BASIC	STI324000-60T	
Simple Technology	BASIC	A324000-60T	
VisionTek Inc.	BASIC	VT69060.0	
		4M x 36 (16MB), Parity -	70ns
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT12D436DM-7	
Micron Technology	FULL	MT12D436DM-70	
Simple Technology	BASIC	STI-XPRESS/16HB	
VisionTek	BASIC	VT69140.0	
Workstation Direct	BASIC	MM4x36-70T12C	
Workstation Birdet	Briolo	4M x 36 (4MB), Parity - 0	
Vandor	Ougl	Vendor Part Number	Comments
Vendor	Qual		Comments
Texas Instruments	FULL	Z497MBK36Q-60	
1st Tech Corporation	BASIC	20-436-60NT3	
1st Tech Corporation	BASIC	20-1040-05	9 DRAMs
		8M x 32 (32MB), Non-Parity	
Vendor	Qual	Vendor Part Number	Comments
Advantage Memory Corp.	BASIC	AMC8x32-70T	
Kingston Technology Corp.	BASIC	KTM8x32L-70T	
Simple Technology	BASIC	STI328000-70T	
Unigen Corporation	BASIC	8x32UG7KBT2	
Viking Components	BASIC	8x32-70T	
VisionTek	BASIC	VT69170.0	
		8M x 32 (32MB), Non-Parity	v - 60ns
Vendor	Qual	Vendor Part Number	Comments
1st Tech Corporation	BASIC	20-832-60NT3	Comments
1st Tech Corporation	BASIC	20-1040-15	<del> </del>
VisionTek Inc.	BASIC	VT69070.0	70
	<del></del>	8M x 36 (32MB), Parity -	
Vendor	Qual	Vendor Part Number	Comments
Simple Technology	BASIC	STI-XPRESS/32HB	
VisionTek	BASIC	VT69180.0	
		8M x 36 (32MB), Parity -	60ns
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT24D836M-6	
1st Tech Corporation	BASIC	20-1040-07	
		•	•

## **EDO SIMM**

Note: 60ns EDO SIMMs are required when the external CPU clock is set to 66 MHz (e.g., for the 100, 133, 166, and 200 MHz Pentium processor). Either 60ns or 70ns SIMMs can be used for external clock frequencies of 50 MHz and 60 MHz, but no additional performance will be seen with the 60ns SIMMs.

Vendor	Qual	Vendor Part Number	Comments
		1M x 32 (4MB), Non-Parity	
Micron Technology	FULL	MT8D132M-7X	
Micron Technology	FULL	MT8D132M-6X	
Samsung Corning Co. Ltd.	FULL	KMM5321004CV-7	4M DRAM Based
Samsung Corning Co. Ltd.	FULL	KMM5321004CV-6	4M DRAM Based
Samsung Corning Co. Ltd.	FULL	KMM5321204AW-7	THI BITT WI BUSCO
Samsung Corning Co. Ltd.	FULL	KMM5321204AW-6	
Smart Modular Technologies	FULL	NI532014081XXS7 or S6	
Texas Instruments	FULL	TM124BBK32U-60	
Texas Instruments	FULL	TM124FBK32U-70	new mask fix
Texas Instruments	FULL	Z124FBK32S-70	Hew HidSK HX
Simple Technology, Inc.	BASIC	STI321004A-70T	1-800-367-7330
1 0,7:			1-000-307-7330
Viking Components	BASIC	EDO1327T	0000
Vandan	0::-1	1M x 32 (4MB), Non-Parity	
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT8D132M-6X	
NEC ELECTRONICS INC	FULL	DRAM(4218165-60)	1011001110
Samsung Corning Co. Ltd.	FULL	KMM5321204AW-6	16M DRAM Based
Samsung Corning Co. Ltd.	FULL	KMM5321004CV-6	4M DRAM Based
Smart Modular Technologies	FULL	NI532014081XXS6	
1st Tech Corporation	BASIC	20-1039-09	
Advantage Memory Corp.	BASIC	AMC1x32-60TEDO	
Kingston Technology Corp.	BASIC	KTM1x32L-60ET	
Simple Technology	BASIC	STI321004-60T	
Simple Technology	BASIC	STI321004T-60T	
Simple Technology	BASIC	A321004-60T	
Unigen Corporation	BASIC	1x32UG6DBT-EDO	
VisionTek Inc.	BASIC	VT69210.0	
		2M x 32 (8MB), Non-Parity	- 70ns
Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	Vendor Part Number MT16D232M-7X	Comments
			Comments
Micron Technology Micron Technology Micron Technology	FULL FULL FULL	MT16D232M-7X	
Micron Technology Micron Technology	FULL FULL	MT16D232M-7X MT8D232M-7X	Comments  1mx4 based
Micron Technology Micron Technology Micron Technology	FULL FULL FULL	MT16D232M-7X MT8D232M-7X MT8D232M-6X	
Micron Technology Micron Technology Micron Technology Smart Modular Technologies	FULL FULL FULL FULL	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7	1mx4 based
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument	FULL FULL FULL FULL FULL	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70	1mx4 based
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd.	FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7	1mx4 based new mask fix
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc.	FULL FULL FULL FULL BASIC BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components	FULL FULL FULL FULL BASIC BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components	FULL FULL FULL FULL BASIC BASIC BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components	FULL FULL FULL FULL BASIC BASIC BASIC  Qual	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies	FULL FULL FULL FULL BASIC BASIC BASIC BASIC FULL FULL FULL FULL FULL FULL	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies	FULL FULL FULL FULL BASIC BASIC BASIC BASIC FULL FULL FULL FULL FULL	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd.	FULL FULL FULL FULL BASIC BASIC BASIC BASIC FULL FULL FULL FULL FULL FULL	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation	FULL FULL FULL FULL BASIC BASIC BASIC BASIC FULL FULL FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp.	FULL FULL FULL BASIC BASIC BASIC BASIC FULL FULL FULL FULL FULL BASIC BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc.	FULL FULL FULL BASIC BASIC BASIC  Gual FULL FULL FULL FULL BASIC BASIC BASIC BASIC BASIC BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC BASIC BASIC BASIC BASIC BASIC BASIC BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd.	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology Simple Technology	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004AT-60T	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004AT-60T 2x32UG6DBT-EDO	1mx4 based new mask fix 1-800-367-7330
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology Simple Technology Unigen Corporation	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004AT-60T 2x32UG6DBT-EDO VT69220.0	1mx4 based new mask fix  1-800-367-7330  - 60ns  Comments
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology Simple Technology Unigen Corporation	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004T-60T STI322004AT-60T 2x32UG6DBT-EDO VT69220.0 4M x 32 (16MB), Non-Parity	1mx4 based new mask fix  1-800-367-7330  - 60ns  Comments
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology Simple Technology Unigen Corporation VisionTek Inc.	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004T-60T STI322004AT-60T 2x32UG6DBT-EDO VT69220.0 4M x 32 (16MB), Non-Parity	1mx4 based new mask fix  1-800-367-7330 60ns  Comments  y-70ns  Comments
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology Simple Technology Unigen Corporation VisionTek Inc.	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004T-60T STI322004AT-60T 2x32UG6DBT-EDO VT69220.0 4M x 32 (16MB), Non-Parity Vendor Part Number	1mx4 based new mask fix  1-800-367-7330  - 60ns  Comments  y-70ns
Micron Technology Micron Technology Micron Technology Smart Modular Technologies Texas Instrument Samsung Corning Co. Ltd. Simple Technology, Inc. Viking Components  Vendor Micron Technology Samsung Corning Co. Ltd. Smart Modular Technologies 1st Tech Corporation Advantage Memory Corp. Celestica Inc. Kingston Technology Corp. NEC Samsung Corning Co. Ltd. Simple Technology Simple Technology Unigen Corporation VisionTek Inc.	FULL FULL FULL BASIC BASIC BASIC FULL FULL FULL FULL FULL FULL FULL BASIC	MT16D232M-7X MT8D232M-7X MT8D232M-6X NI532024081XXS7 TM248GBK32U-70 KMM5322104AU-7 STI322004A-70T EDO2327T 2M x 32 (8MB), Non-Parity Vendor Part Number MT16D232M-6X KMM5322204BW-6 NI532024081XXS6 20-1039-11 AMC2x32-60TEDO CL001D02325B00J-60 KTM2x32L-60ET MC-422000F32BA-60 KMM5322104AU-6 STI322004T-60T STI322004T-60T STI322004AT-60T 2x32UG6DBT-EDO VT69220.0 4M x 32 (16MB), Non-Parity	1mx4 based new mask fix  1-800-367-7330 60ns  Comments  y-70ns  Comments

4M x 32 (16MB), Non-Parity - 60ns

Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT8D432M-6X	
Micron Technology	FULL	MT8D432M-60X	
Samsung Corning Co. Ltd.	FULL	KMM5324104AK-6	
Texas Instruments	FULL	TM497FBK32S-60	
1st Tech Corporation	BASIC	20-1040-17	
Advantage Memory Corp.	BASIC	AMC4x32-60TEDO	
Celestica Inc.	BASIC	CL001D04325B00J-60	
Kingston Technology Corp.	BASIC	KTM4x32L-60ET	
Simple Technology	BASIC	STI324004-60T	
Simple Technology	BASIC	STI324004T-60T	
Simple Technology	BASIC	A324004-60T	
VisionTek Inc.	BASIC	VT69240.0	

8M x 32 (32MB), Non-Parity - 70ns

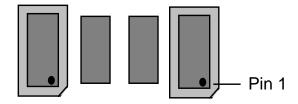
Vendor	Qual	Vendor Part Number	Comments
1st Tech Corporation	BASIC	20-1026-02	
Simple Technology, Inc.	BASIC	STI328004-70T	1-800-367-7330

8M x 32 (32MB), Non-Parity - 60ns

Vendor	Qual	Vendor Part Number	Comments
Micron Technology	FULL	MT16D832M-60X	
Samsung Corning Co, LTD.	FULL	KMM5328104BK-6	
1st Tech Corporation	BASIC	20-1040-21	
Advantage Memory Corp.	BASIC	AMC8x32-60TEDO	
Kingston Technology Corp.	BASIC	KTM8x32L-60ET	
Simple Technology	BASIC	STI328004-60T	
Simple Technology	BASIC	STI328004T-60T	
VisionTek Inc.	BASIC	VT69280.0	

## **GRAPHICS MEMORY**

The Advanced/MA baseboard has 1 MB of Fast Page DRAM installed for graphics and two SOJ type sockets for upgrades up to 2 MB of graphics DRAM. The user can install two 256k x 16, 60 nS DRAM to provide a total of 2 MB of graphics DRAM. The DRAM may be either EDO or Fast Page mode, but no performance advantage will be seen with EDO.



Vendor	Qual	Vendor Part Number	Comments		
Fast Page Video DRAM (256Kx16, 60ns, SOJ)					
Hyundai	FULL	HY514260BJC-60R			
Micron Technology	FULL	MT4C16257DJ-6TR			

### EDO Video DRAM (256Kx16, 60ns, SOJ)

Vendor	Qual	Vendor Part Number	Comments
Etron Technology Inc.	FULL	EM614163A-60	
Micron Technology	FULL	MT4C16270DJ-6	
Samsung Corning Co.,Ltd	FULL	KM416C254BJ-6T	

## REAL TIME CLOCK BATTERY REPLACEMENT

The battery can be replaced with a Sanyo CR2032, or equivalent, coin cell lithium battery. This battery has a 220 mAh rating.

### APPROVED BATTERY VENDORS

Vendor	Qual	Vendor Part Number	Comments
		Battery, Coin cell, CR2032	
Maxell Corporation	FULL	CR2032	
Panasonic Industrial Company	FULL	CR2032	
Renata Batteries U.S.	FULL	CR2032	
Sanyo Energy Corp	FULL	CR2032	
Sony Corp	FULL	CR-2032	

### OVERDRIVE PROCESSOR SUPPORT MATRIX

The information below describes the specific OPSD systems that support the OverDrive 320-pin PODP 3V-XXX processors which can be accommodated in a 320 pin Type 5 Socket or a 321 pin Type 7 Socket. The tables list the jumper settings required for the selected OverDrive processors. These OverDrive processors select their clock ratios internally and do not use the baseboard's internal clock ratio jumpers. These OverDrive processors work over a voltage range that includes both VR and VRE voltage ranges, therefore the user does not need to change the voltage specification jumpers on the baseboard.

For any particular baseboard, the type and speed of memory and/or the speed of the cache components that are used on the baseboard, may limit a baseboards' maximum achievable External CPU Clock speed. This would then limit the selection of Pentium OverDrive processor that could be used to full effect on this particular baseboard. Use the current external CPU clock settings as a guide in selecting a compatible selection for a Pentium OverDrive processor speed.

The Advanced/MA baseboard has a 321-pin Type 7 Zero Insertion Force (ZIF) socket which may provide users with an OverDrive processor performance upgrade path.

PROCESSOR UPGRADES	Original	External CPU Clock	Host Bus Frequency Jumper
СРИ Туре	СРИ Туре	Speed	J5J1
Intel PODP 3V - 125 MHz	75 MHz	50 MHz	pins 1-2, 4-5
Intel PODP 3V - 150 MHz	90 MHz	60 MHz	pins 1-2, 5-6
Intel PODP 3V - 166 MHz	100 MHz	66 MHz	pins 2-3, 4-5

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